# **Panasonic**

## DB2G43200L

#### For rectification

#### ■ Features

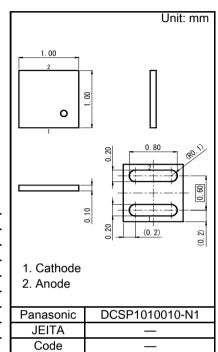
- Low forward voltage VF
- Forward current (Average) IF(AV) ≤ 2.0 A rectification is possible
- RoHS compliant (EU RoHS / MSL:Level 1 compliant)
- Marking Symbol: D8

#### Packaging

Embossed type (Thermo-compression sealing): 20 000 pcs / reel (standard)

#### ■ Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit
Reverse Voltage *1	VR	-	40	V
Maximum Peak Reverse Voltage *1	VRM	-	40	V
Average Forward Current *2,3	IF(AV)	-	2.0	Α
Average Forward Current *2,4	IF(AV)	-	2.0	Α
Non-repetitive Peak Surge Forward Current *1,5	IFSM	-	20	Α
Operating Junction Temperature *6	Tj	-	150	°C
Ambient Temperature	Та	-40	+150	°C
Storage Temperature	Tstg	-55	+150	°C



- Note) \*1: Ta = Tj = 25°C
  - \*2: Square wave :  $\sigma$  = 0.5
  - \*3: Ta ≦ 38°C, when device mounted on a FR4 PCB (25.4mm×25.4mm, 1mm thick), copper wiring (608.0mm² area, 36μm thick).
  - \*4: Solder Point Temperature : Tsp ≦ 130°C
  - \*5: Square wave : Tp = 5 ms
  - \*6: Power derating is necessary so that Tj < 150°C.

(Waveform definition)	IF <b>↑</b> ← Top
Duty Cycle : $\sigma = \frac{Tp}{T}$	
	Time

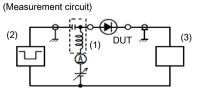
#### ■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward Voltage	VF	IF = 2.0 A	-	0.45	0.52	V
Reverse Current	IR	VR = 40 V	-	90	400	μA
Terminal Capacitance	Ct	VR = 10 V, f = 1 MHz	-	47	-	pF
Reverse Recovery Time *1	trr	IF = IR = 100 mA, Irr = 10 mA	-	14	-	ns

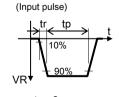
- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
  - 2. This product is sensitive to electric shock (static electricity, etc.).

Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. \*1: Measurement circuit, input pulse, output pulse for Reverse recovery time

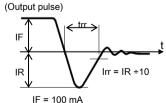


- (1) Bias Insertion Unit (N-50BU)
- (2) Pulse Generator (PG-10N), RS =  $50 \Omega$
- (3) Wave Form Analyzer (SAS-8130), Ri =  $50 \Omega$



 $tp = 2 \mu s$ tr = 0.35 ns

 $\sigma = 0.05$ 



IR = 100 mA

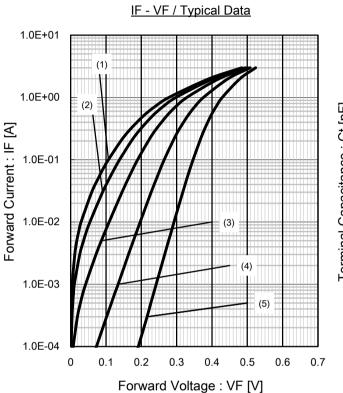
Irr = 10 mA

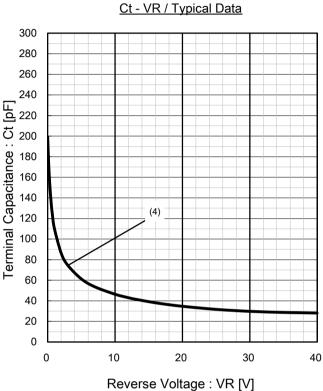
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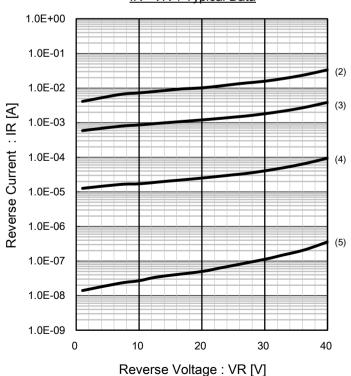
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## Electrical Characteristics Technical Data (Reference)





IR - VR / Typical Data



(Graph legends)

(1)	Ta =	150	°C
(2)	Ta =	125	°C
(3)	Ta =	85	°C
(4)	Ta =	25	°C
(5)	Ta =	-40	°C

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## Electrical Characteristics Technical Data (Reference)

PF(AV) - IF(AV) / Typical Data 3.0 Tj = 25°C (Waveform definition) (1) (2) Duty Cycle :  $\sigma = \frac{Tp}{T}$ (3)(4) (Graph legends) σ= 1.0 σ= 0.8 (3)  $\sigma$ = 0.5 (4)  $\sigma = 0.3$ 0.5 1.0 1.5 2.5 0.0 3.0

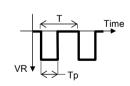
Average Forward Current : IF(AV) [A]

PR(AV) - VR / Typical Data

# 0.00500 M Tj = 25°C Tj = 25°C (1) (2) (3) (4)

Reverse Voltage : VR [V]

(Waveform definition)



Duty Cycle :  $\sigma = \frac{Tp}{T}$ 

(Graph legends)
(1)  $\sigma$ = 1.0
(2)  $\sigma$ = 0.7
(3)  $\sigma$ = 0.5
(4)  $\sigma$ = 0.2

40

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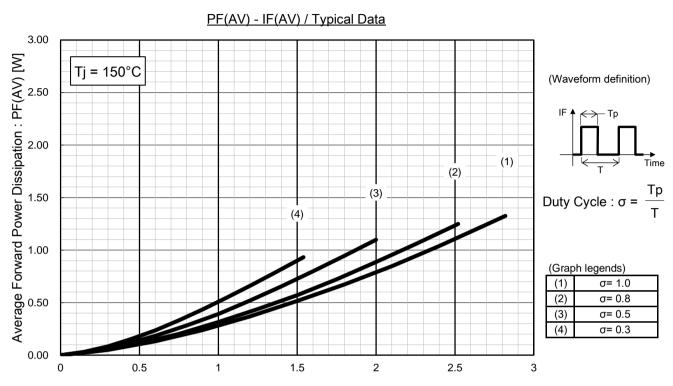
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0.00000

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## Electrical Characteristics Technical Data (Reference)



Average Forward Current : IF(AV) [A]

#### PR(AV) - VR / Typical Data 1.50 Average Reverse Power Dissipation: PR(AV) [W] (1) Tj = 125°C (Waveform definition) 1.00 (2) Duty Cycle : $\sigma = \frac{Tp}{T}$ (3) 0.50 (Graph legends) σ= 1.0 (4) σ= 0.7 (3) $\sigma$ = 0.5 $\sigma$ = 0.2 0.00 10 20 40

Reverse Voltage: VR [V]

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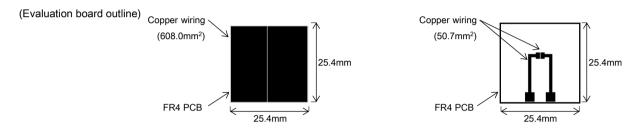
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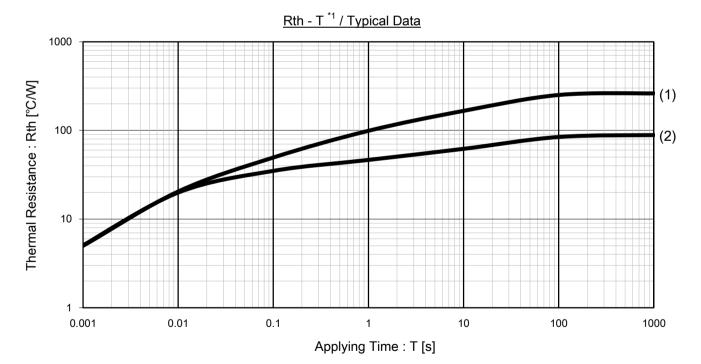
#### ■ Thermal Characteristics

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Thermal Resistance, Junction to Solder Point	$R_{th(j-sp)}$	Ta = 25°C, in free air	1	15	1	°C/W
Thermal Resistance, Junction to Ambient *1	R <sub>th(j-a)</sub>	Ta = 25°C, in free air	ı	88	ı	°C/W
Thermal Resistance, Junction to Ambient *2	R <sub>th(j-a)</sub>	Ta = 25°C, in free air	-	262	-	°C/W

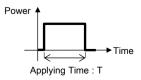
- Note) \*1: Device mounted on a FR4 PCB (25.4mm×25.4mm, 1mm thick), copper wiring (608.0mm² area, 36µm thick).
  - \*2: Device mounted on a FR4 PCB (25.4mm×25.4mm, 1mm thick), copper wiring (50.7mm<sup>2</sup> area, 36µm thick).



## Thermal Characteristics Technical Data (Reference)



Note) \*1: Single pulse measurement (Waveform definition)



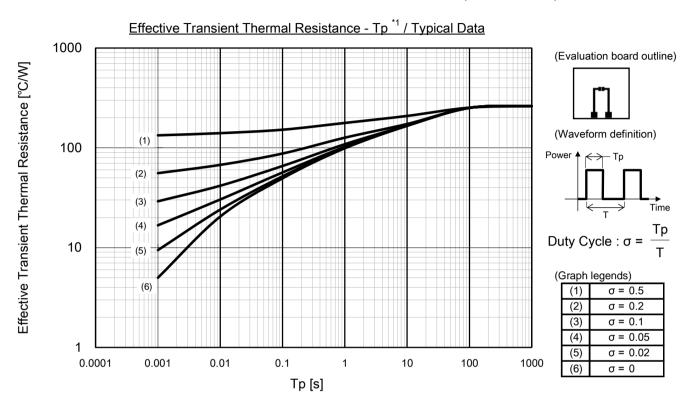
(Graph legends)

(4)		Device mounted on a FR4 PCB (25.4mm×25.4mm, 1mm thick),
ı	(1)	conner wiring (50 7mm <sup>2</sup> area, 36µm thick)
(2)		Device mounted on a FR4 PCB (25.4mm, 25.4mm, 1mm thick),
(2)	(2)	copper wiring (608.0mm <sup>2</sup> area, 36µm thick).

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## Thermal Characteristics Technical Data (Reference)



#### Effective Transient Thermal Resistance - Tp \*2 / Typical Data 1000 (Evaluation board outline) Effective Transient Thermal Resistance [°C/W] (Waveform definition) 100 (1) (2) Duty Cycle : σ = (3) 10 (5) (Graph legends) (6) $\sigma = 0.5$ $\sigma = 0.2$ $\sigma = 0.1$ $\sigma = 0.05$ $\sigma = 0.02$ 0.0001 0.001 0.01 0.1 1 10 100 1000 Tp[s]

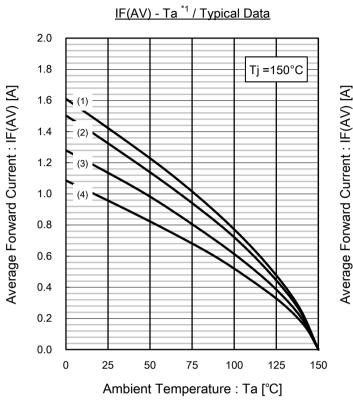
Note) \*1: Device mounted on a FR4 PCB (25.4mm×25.4mm, 1mm thick), copper wiring (50.7mm² area, 36µm thick).

\*2: Device mounted on a FR4 PCB (25.4mm×25.4mm, 1mm thick), copper wiring (608.0mm<sup>2</sup> area, 36µm thick).

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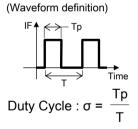
## Power Derating Technical Data (Reference)



IF(AV) - Ta \*2 / Typical Data 3.5 Tj =150°C 3.0 (1) -2.5 2.0 1.5 1.0 0.5 0.0 25 50 75 100 125 150 Ambient Temperature : Ta [°C]

IF(AV) - Tsp / Typical Data 3.5 Tj =150°C 3.0 Average Forward Current: IF(AV) [A] 2.5 2.0 (3) 1.5 1.0 0.5 0.0 25 50 75 100 150 125 Solder Point Temperature : Tsp [°C]

(Graph legends)					
(1)	σ = 1.0				
(2)	$\sigma = 0.8$				
(3)	$\sigma = 0.5$				
(4)	σ = 0.3				



#### Note)

\*1: Device mounted on a FR4 PCB (25.4mm×25.4mm, 1mm thick), copper wiring (50.7mm² area, 36µm thick).

(Evaluation board outline)



\*2: Device mounted on a FR4 PCB (25.4mm×25.4mm, 1mm thick), copper wiring (608.0mm² area, 36µm thick).

(Evaluation board outline)



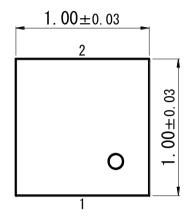
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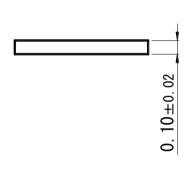
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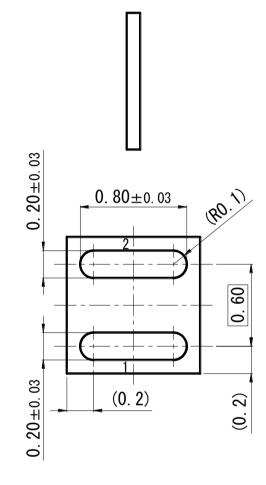
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## DCSP1010010-N1

Unit: mm

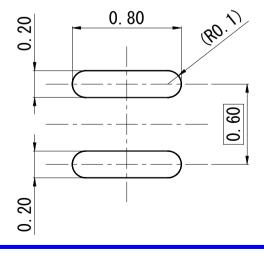






### ■ Land Pattern (Reference)

Unit: mm



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